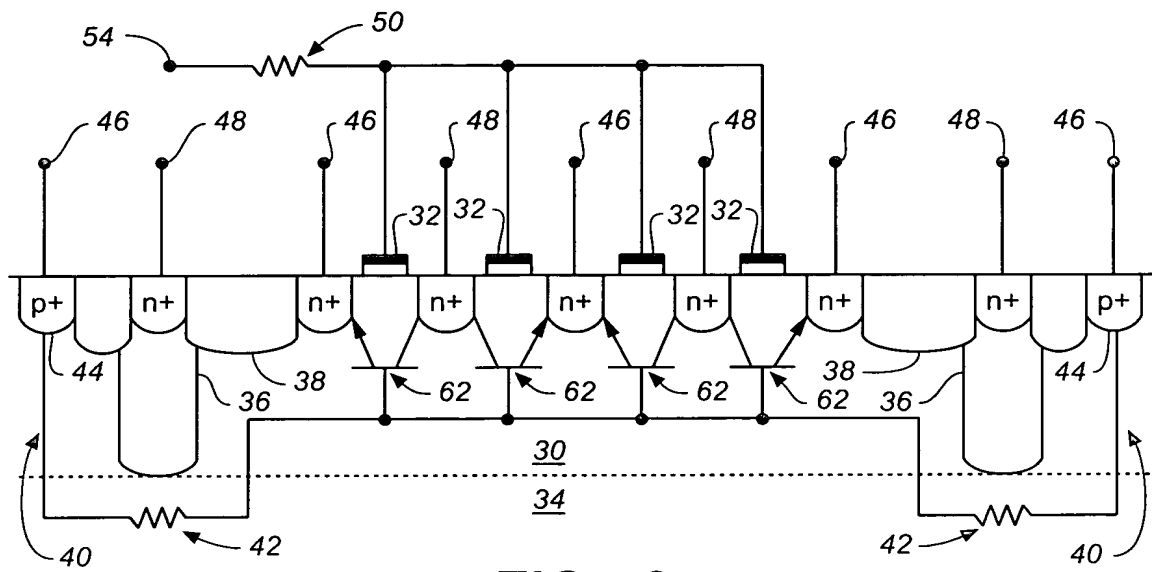


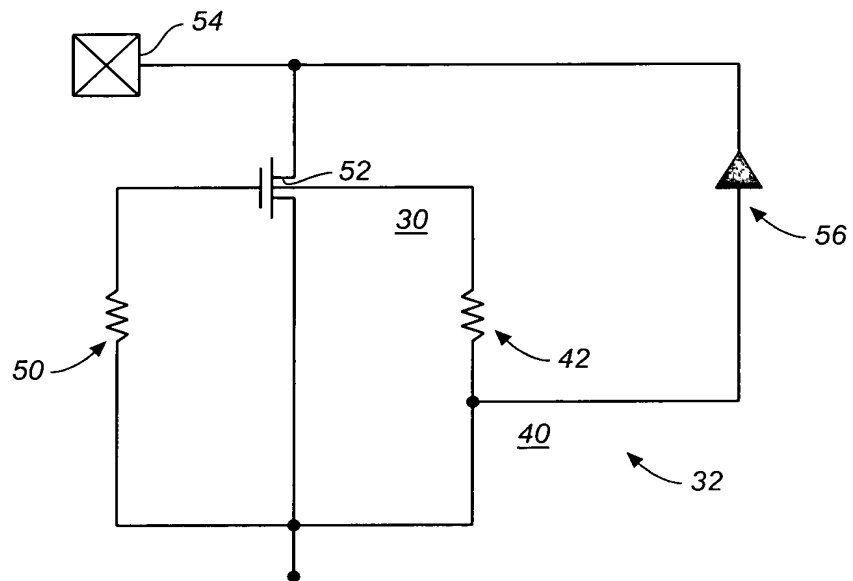
A cross-sectional view of a semiconductor device. The device features a series of alternating n+ regions and p+ regions. The n+ regions are connected to a common ground line (22) via resistors (24). The p+ regions are connected to a common power line (28) via resistors (24). The device includes various electrical connections and labels: 14, 16, 10, 18, 20, 26, and 28. The device is shown in a cross-sectional view with a dashed line indicating the bottom surface.

This diagram shows a cross-sectional view of a multi-layered rectangular structure. At the center is a core region labeled 30, which contains a series of vertical, parallel bars labeled 36. Surrounding the core is a thick, textured layer labeled 38. This layer is further enclosed by a thin white layer labeled 44. The entire assembly is bounded by a thick, textured outer frame labeled 3. Arrows point from the labels 3, 30, 36, 38, and 44 to their respective components.

 $+$



**FIG.\_3**



**FIG.\_4**

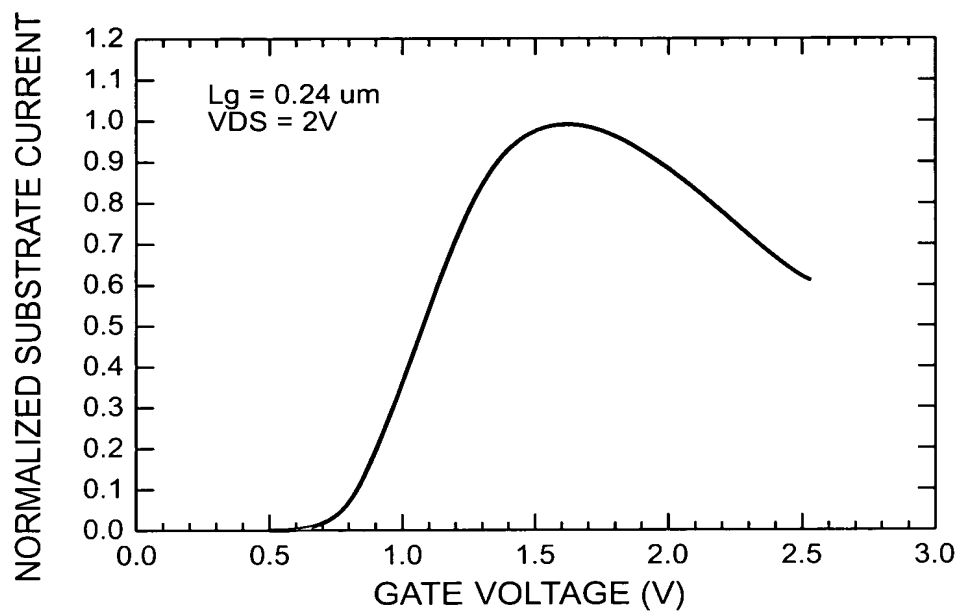


FIG. 5

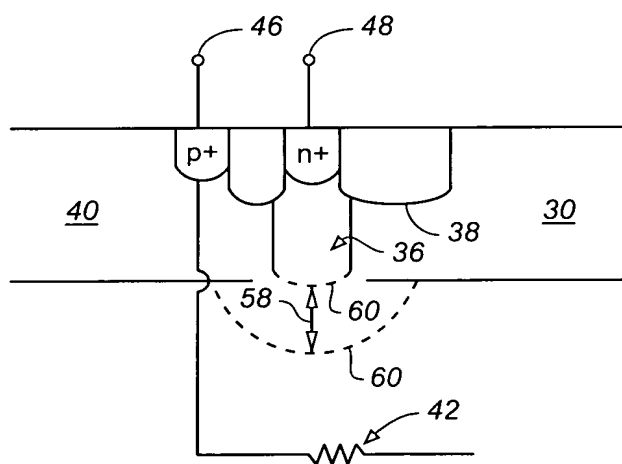
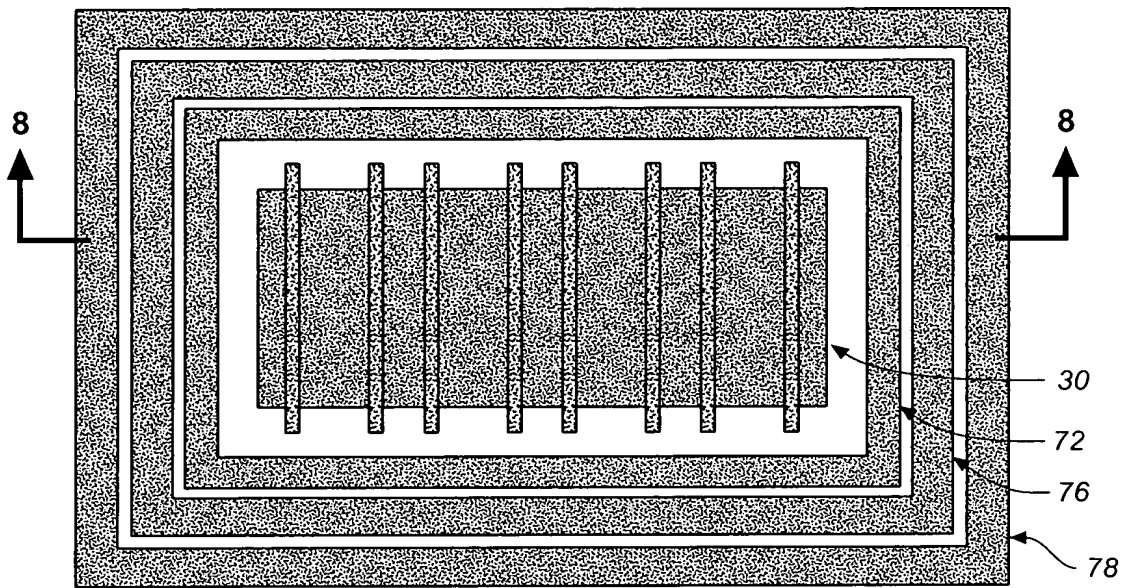


FIG. 6



**FIG.\_7**

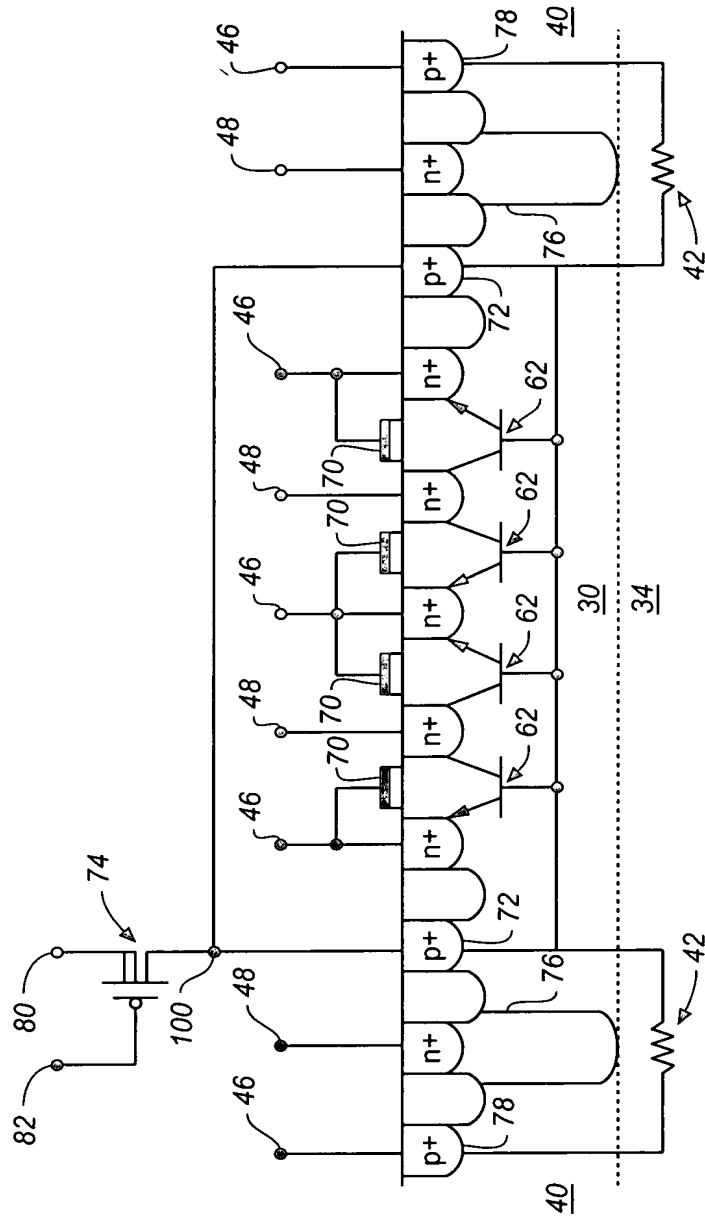
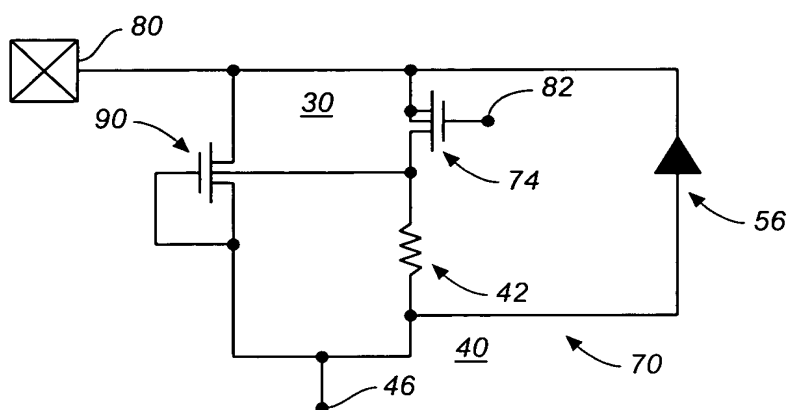
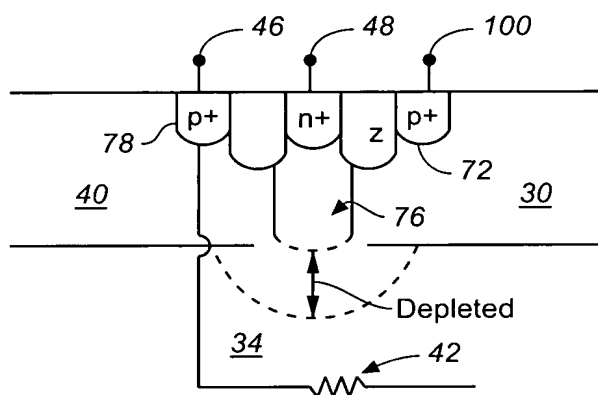


FIG. 8

**FIG. 9****FIG. 10**